

## Mask Set Errata for Mask 0M03Y

### Introduction

This report applies to mask 0M03Y for these products:

- MPC5605B
- MPC5606B
- MPC5607B

Prior ID	Current ID	Erratum Title
	e4168	ADC: "Abort switch" aborts the ongoing injected channel as well as the upcoming normal channel
e5485	e3069	ADC: ADC_DMAE[DCLR] set to 1 clears the DMA request incorrectly
e5883	e3080	ADC: CTUEN bit in ADC.MCR register cannot be reset if a BCTU channel is enabled
	e4186	ADC: triggering an ABORT or ABORTCHAIN before the conversion starts
e9984	e3446	CTU : The CTU (Cross Trigger Unit) CLR_FLAG in EVTCFGR register does not function as expected
	e3449	DEBUG: Device may hang due to external or 'functional' reset while using debug handshaking mechanism
e6841	e3149	Diode path between VDD_LV and VDD_HV
	e3556	DMA_MUX : Low Power Entry may not be completed when peripherals run on divided clock with DMA enabled mode
e10637	e3512	ECSM: ECSM_PFEDR displays incorrect endianness
e5008	e3041	FLASH: Array Integrity Check does not check the first two double words
e5060	e3047	FLASH: Double ECC errors of default Non Volatile image of BIU2 (PFCR2/PFAPR) are not checked
e7587	e3183	FLASH: Erase Suspend Latency is out of spec in Flash except Code Flash 0.
e5673	e3073	FLASH: Margin Mode is not supported
e5007	e3040	FLASH: Programming a value over another value may not indicate an error if no bits are being programmed (1-->0)
e5034	e3045	FLASH: SLL and HBL not properly initialized
	e2656	FlexCAN: Abort request blocks the CODE field

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Prior ID	Current ID	Erratum Title
	e3407	FlexCAN: CAN Transmitter Stall in case of no Remote Frame in response to Tx packet with RTR=1
e1685	e2883	FMPLL: FMPLL_CR[UNLOCK_ONCE] wrongly set
e8906	e3233	IDD issue in STANDBY when OSC32K is enabled
e8099	e3195	LINFlex: Limitations for DMA access to LINFlex
e4781	e3021	LINFlex: Unexpected LIN timeout in slave mode
	e4340	LINFlexD: Buffer overrun can not be detected in UART Rx FIFO mode
e10107	e3466	LINFlexD: Register bus aborts are not generated on illegal accesses to reserved addresses within the register address space of LINFlexD
e8761	e3219	MC_CGM: System clock may stop for case when target clock source stops during clock switching transition
e8350	e3202	MC_ME: Invalid Configuration not flagged if PLL is on while OSC is off.
e7776	e3190	MC_ME: Main VREG not disabled during STOP0 or HALT0 mode if RUN[0..3] mode selects FXOSC to be running and target mode selects FXOSC as system clock
	e3570	MC_ME: Possibility of Machine Check on Low-Power Mode Exit
e9140	e3247	MC_ME: STANDBY0/HALT0/STOP0 modes cannot be entered if the FlexCAN peripheral is active
e10491	e3574	MC_RGM: A non-monotonic ramp on the VDD_HV/BV supply can cause the RGM module to clear all flags in the DES register
e2835	e2958	MC_RGM: Clearing a flag at RGM_DES or RGM_FES register may be prevented by a reset
e5095	e3049	MC_RGM: External Reset not asserted if Short Reset enabled
e3492	e2977	MC_RGM: Long Reset Sequence Occurs on 'Short Functional' Reset Event
e5301	e3060	MC_RGM: SAFE mode exit may be possible even though condition causing the SAFE mode request has not been cleared
e8499	e3209	NMI pin configuration limitation in standby mode
e8500	e3210	PA[1] pull-up enabled when NMI activated
e9073	e3242	PB[10],PD[0:1] pins configuration during standby
e8329	e3200	PIT events cannot be used to trigger ADC conversion incase BCTU runs on divided system clock
e9486	e3270	Risk of increased Analog to Digital converter pad leakage under extreme current injection conditions
e9725	e4405	SR bit of LINFlexD GCR register is not cleared automatically by hardware
e6440	e3119	SWT: SWT interrupt does not cause STOP0 mode exit
e8948	e3236	Wakeup line functionality on PD[0], PD[1] not available in STANDBY
	e4146	When an ADC conversion is injected, the aborted channel is not restored under certain conditions

Revision	Changes
25AUG2011	Initial revision

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Revision	Changes
17MAY2012	<p>The following errata were removed.</p> <ul style="list-style-type: none"> <li>• e3442: Now described in RM</li> </ul> <p>The following errata were added.</p> <ul style="list-style-type: none"> <li>• e4405: New errata</li> <li>• e4340: New errata</li> <li>• e4146: New errata</li> <li>• e4186: New errata</li> <li>• e4168: New errata</li> </ul> <p>The following errata were revised.</p> <ul style="list-style-type: none"> <li>• e3512: Description updated for clarity</li> <li>• e3570: Description updated for clarity</li> <li>• e3200: Description updated for clarity</li> </ul>

### **e4168: ADC: "Abort switch" aborts the ongoing injected channel as well as the upcoming normal channel**

**Description:** If an Injected chain (jch1,jch2,jch3) is injected over a Normal chain (nch1,ch2,ch3,ch4) the Abort switch doesn't behave as expected.

Expected behavior:

\* Correct Case (without SW Abort on jch3): Nch1, Nch2(aborted), Jch1, Jch2, Jch3, Nch2(restored), Nch3, Nch4

\* Correct Case(with SW Abort on jch3): Nch1, Nch2(aborted), Jch1, Jch2, Jch3(aborted), Nch2(restored), Nch3, Nch4

Observed unexpected behavior:

\* Fault1 (without SW abort on jch3): Nch1, Nch2(aborted), Jch1, Jch2, Jch3, Nch3, Nch4 (Nch2 not restored)

\* Fault2 (with SW abort on jch3): Nch1, Nch2, Jch1, Jch2, Jch3(aborted), Nch4 (Nch2 not restored & Nch3 conversion skipped)

**Workaround:** It is possible to detect the unexpected behavior by using the CEOCFRx register. The CEOCFRx fields will not be set for a not restored or skipped channel, which indicates this issue has occurred. The CEOCFRx fields need to be checked before the next Normal chain execution (in scan mode). The CEOCFRx fields should be read by every ECH interrupt at the end of every chain execution.

### **e3069: ADC: ADC\_DMAE[DCLR] set to 1 clears the DMA request incorrectly**

**Description:** When ADC\_DMAE[DCLR] is set the DMA request should be cleared only after the data registers are read. However for this case the DMA request is automatically cleared and will not be recognised by the eDMA.

**Workaround:** None

**e3080: ADC: CTUEN bit in ADC.MCR register cannot be reset if a BCTU channel is enabled**

**Description:** While any BCTU channels is enabled (CTU.EVTCFGRx.TM =1), the CTU will continuously send trigger requests to ADC. If CTUEN bit in MCR is reset while BCTU channels are enabled, the ADC DTU trigger state may become undefined and ADC module may not service trigger request from CTU anymore.

**Workaround:** Ensure ADC.MCR.CTUEN is set before enabling any CTU channels (CTU.EVTCFGRx.TM =1). Ensure all CTU channels are disabled (CTU.EVTCFGRx.TM =0) before ADC.MCR.CTUEN is cleared.

**e4186: ADC: triggering an ABORT or ABORTCHAIN before the conversion starts**

**Description:** When ABORTCHAIN is programmed and an injected chain conversion is programmed afterwards, the injected chain is aborted, but neither JECH is set, nor ABORTCHAIN is reset. In case a CTU conversion is demanded, the CTU conversion is aborted by the ADC digital logic but the CTU awaits ADC analogue acknowledgement that never arrives, stopping all CTU operation until next reset.

When ABORT is programmed and normal/injected chain conversion comes afterwards, the ABORT bit is reset and chain conversion runs without a channel abort.

If ABORT, or ABORTCHAIN, feature is programmed after the start of the chain conversion, it works properly.

**Workaround:** Do not program ABORT/ABORTCHAIN before starting the execution of the chain conversion.

If the CTU is being used in trigger mode, there will always be a small vulnerable window preventing reliably reading the ADC status and using ADC.MCR[ABORT] or ADC.MCR[ABORTCHAIN]. If these functions are required, disable all CTU triggers to that ADC first and do not start the CTU if the ABORT or ABORTCHAIN flags have been set whilst the ADC was IDLE. If the CTU cannot be disabled, an optimised ABORT should be implemented in software that de-configures further channel conversions using the ADC.NMCRx registers before waiting for ADC.MSR[NSTART] == 0. At this point, the ADC should be IDLE and the NMCRx registers can be reinstated for next use.

**e3446: CTU : The CTU (Cross Trigger Unit) CLR\_FLAG in EVTCFGR register does not function as expected**

**Description:** If the CTU CLR\_FLG is set and the CTU is idle, a PIT triggered request to the CTU does not result in the correct ADC channel number being latched. The previous ADC channel number is latched instead of the requested channel number.

**Workaround:** There is no software workaround to allow the CLR\_FLAG functionality to operate correctly. Do not program the CLR\_FLAG bit to '1'.

### **e3449: DEBUG: Device may hang due to external or 'functional' reset while using debug handshaking mechanism**

**Description:** If the low-power mode debug handshake has been enabled and an external reset or a 'functional' reset occurs while the device is in a low-power mode, the device will not exit reset.

**Workaround:** The NPC\_PCR[LP\_DBG\_EN] bit must be cleared to ensure the correct reset sequence.

### **e3149: Diode path between VDD\_LV and VDD\_HV**

**Description:** The design implements diodes between VDD\_LV and VDD\_HV. This leads to current flowing from VDD\_LV to VDD\_HV if power-up and power-down sequences are not handled correctly. VDD\_LV to VDD\_HV current may stress the device and should be avoided when possible

**Workaround:** Insert a schottky diode between VDD\_LV and VDD\_HV

### **e3556: DMA\_MUX : Low Power Entry may not be completed when peripherals run on divided clock with DMA enabled mode**

**Description:** System may not enter into Low Power Mode (HALT/STOP/STANDBY) when all the below conditions are true simultaneously:

1. A Peripheral with DMA capability is programmed to work on divided clock.
2. Above peripheral is programmed to be stopped in Low Power Mode and active in RUN Mode.
3. Above Peripheral is active with DMA transfer while Software requests change to Low Power mode.

**Workaround:** Software should ensure that all the DMA enabled peripherals have completed their transfer before requesting Low Power mode Entry

### **e3512: ECSM: ECSM\_PFEDR displays incorrect endianness**

**Description:** The ECSM\_PFEDR register reports ECC data using incorrect endianness. For example, a flash location that contains the data 0xAABBCCDD would be reported as 0xDDCCBBAA at ECSM\_PFEDR.

This 32-bit register contains the data associated with the faulting access of the last, properly-enabled flash ECC event. The register contains the data value taken directly from the data bus.

**Workaround:** Software must correct endianness.

### **e3041: FLASH: Array Integrity Check does not check the first two double words**

**Description:** The Array Integrity Check operation, started by setting the bit Array Integrity Enable (AIE) in the FLASH User Test 0 register (FLASH\_UT0) on the selected and unlocked blocks, checks the content of all the blocks selected except for the first two double words of each block (offsets 0x0 and 0x8).

The first location checked of each block is at the offset 0x10.

**Workaround:** The application should take care of checking the first two double words of each block selected for the Array Integrity Check operation.

### **e3047: FLASH: Double ECC errors of default Non Volatile image of BIU2 (PFCR2/PFAPR) are not checked**

**Description:** The default value of the Flash BIU2 (PFCR2 in the MPC563xM/SPC563M, also named PFAPR in MPC560xB/C/P/S or SPC560B/C/P/S) register is loaded from a non-volatile memory (NVM) area. However, when this value is loaded into the BIU2 register, the presence of Double Errors in the Error Correction Code (ECC) value is not checked.

If the NVM area contains a double bit error, incorrect data will be loaded.

On the contrary single ECC errors are automatically corrected.

**Workaround:** Do not rely on the contents of the BIU2 (PFCR2/PFAPR) to automatically be loaded into the register correctly. Software should always load the User defined value manually into the register.

### **e3183: FLASH: Erase Suspend Latency is out of spec in Flash except Code Flash 0.**

**Description:** The Erase Suspend Latency is out of spec on all available Flash memories except Code Flash 0. A maximum latency of 34us can occur instead of the specified 30us.

On the contrary the Erase Suspend Latency is correctly in spec in Code Flash 0.

**Workaround:** The wait for the suspend acknowledgement must be done by polling the DONE bit of MCR and not through a wait for a fix delay.

### **e3073: FLASH: Margin Mode is not supported**

**Description:** The flash contains a support for determining the program and erase margin (to being near the actual decision point for reading the bit as a high or low). However, this feature will incorrectly indicate bits in the flash that have plenty of margin as marginal and will not indicate that marginal bits are, in fact, marginal.

**Workaround:** Verification of the flash programming should rely on the Array Integrity feature and the built in Error Correction to determine the state of the flash.

### e3040: FLASH: Programming a value over another value may not indicate an error if no bits are being programmed (1-->0)

**Description:** The Flash Programming/Erase Good Status Flag (PEG) in the Flash Module Configuration Register (Flash\_MCR) may not indicate a failure to program if an attempt is made to program bits high (0b1) that are currently programmed low (0b0) if no bits in the 64-bit word or the 8 bit Error Correction Code (ECC) are being programmed low (to a 0b0).

For example, PEG will not indicate a failure (FLASH\_MCR[PEG]=1) if an attempt is made to program the value 0x5555\_FFFF over a flash location that already was programmed to 0x5555\_5555. The flash contents will not be changed (stays 0x5555\_5555) even though it should fail since there were no bits actually selected to be programmed (cleared).

However, PEG will correctly indicate a failure (FLASH\_MCR[PEG]=0) if an attempt is made to program the value of 0x5555\_00FF over a flash location that was already programmed to 0x5555\_5555. The resulting flash contents will be 0x5555\_0055.

NOTE: Reprogramming bits from a programmed state (0b0) to an erased state (0b1) is not supported on flash memory technology. A bit can only be set (0b1) by erasing the full flash block.

**Workaround:** Do not expect an error to be flagged if there are no bits being cleared (0b0) in the word being programmed when programming a new value into a location in the flash that has already been programmed with a previous (not still erased) value.

### e3045: FLASH: SLL and HBL not properly initialized

**Description:** The Secondary Low/Mid Address Space Block Locking register (SLL) and the High Address Space Block Locking register (HBL) have a non-volatile image stored in Test Flash to allow a default state to be set by the user immediately following reset. These locations are write once only.

During boot, the register SLL and HBL are not loaded with the correct default value from the non-volatile location. This means that the default lock status of the Low, Mid, and High blocks are unknown.

**Workaround:** The application should not rely on the default non-volatile value of SLL and HBL and must initialize both registers with the User defined values.

### e2656: FlexCAN: Abort request blocks the CODE field

**Description:** An Abort request to a transmit Message Buffer (TxMB) can block any write operation into its CODE field. Therefore, the TxMB cannot be aborted or deactivated until it completes a valid transmission (by winning the CAN bus arbitration and transmitting the contents of the TxMB).

**Workaround:** Instead of aborting the transmission, use deactivation instead.

Note that there is a chance the deactivated TxMB can be transmitted without setting IFLAG and updating the CODE field if it is deactivated.

### **e3407: FlexCAN: CAN Transmitter Stall in case of no Remote Frame in response to Tx packet with RTR=1**

**Description:** FlexCAN does not transmit an expected message when the same node detects an incoming Remote Request message asking for any remote answer.

The issue happens when two specific conditions occur:

1) The Message Buffer (MB) configured for remote answer (with code "a") is the last MB. The last MB is specified by Maximum MB field in the Module Configuration Register (MCR[MAXMB]).

2) The incoming Remote Request message does not match its ID against the last MB ID.

While an incoming Remote Request message is being received, the FlexCAN also scans the transmit (Tx) MBs to select the one with the higher priority for the next bus arbitration. It is expected that by the Intermission field it ends up with a selected candidate (winner). The coincidence of conditions (1) and (2) above creates an internal corner case that cancels the Tx winner and therefore no message will be selected for transmission in the next frame. This gives the appearance that the FlexCAN transmitter is stalled or "stops transmitting".

The problem can be detectable only if the message traffic ceases and the CAN bus enters into Idle state after the described sequence of events.

There is NO ISSUE if any of the conditions below holds:

- a) The incoming message matches the remote answer MB with code "a".
- b) The MB configured as remote answer with code "a" is not the last one.
- c) Any MB (despite of being Tx or Rx) is reconfigured (by writing its CS field) just after the Intermission field.
- d) A new incoming message sent by any external node starts just after the Intermission field.

**Workaround:** Do not configure the last MB as a Remote Answer (with code "a").

### **e2883: FMPLL: FMPLL\_CR[UNLOCK\_ONCE] wrongly set**

**Description:** If the FMPLL is locked and a functional reset occurs, FMPLL\_CR[UNLOCK\_ONCE] is automatically set even when the FMPLL has not lost lock.

**Workaround:** Do not use the FMPLL\_CR[UNLOCK\_ONCE] when a functional reset occurs.

### **e3233: IDD issue in STANDBY when OSC32K is enabled**

**Description:** When OSC32K is running standby mode, short circuit current of 50nA to 250uA is possible on VDD\_HV. This value is just for typical conditions (25C, 5.5V). This problem of high current exists only during standby mode. All other modes are not affected by this issue.

**Workaround:** None



### **e3195: LINFlex: Limitations for DMA access to LINFlex**

**Description:** The DMA handshaking to the LINFlex can fail when the LINFlex operates on a divided peripheral clock.

**Workaround:** Don't divide the LINFlex peripheral clock if DMA access is required.

### **e3021: LINFlex: Unexpected LIN timeout in slave mode**

**Description:** If the LINFlex is configured in LIN slave mode, an unexpected LIN timeout event (LINESR[OCF]) may occur during LIN Break reception.

**Workaround:** It is recommended to disable this functionality during LINFlex initialization by clearing LINTCSR[IOT] and LINIER[OCIE] bits, and ignore timeout events.

### **e4340: LINFlexD: Buffer overrun can not be detected in UART Rx FIFO mode**

**Description:** When the LINFlexD is configured in UART Receive (Rx) FIFO mode, the Buffer Overrun Flag (BOF) bit of the UART Mode Status Register (UARTSR) register is cleared in the subsequent clock cycle after being asserted.

User software can not poll the BOF to detect an overflow.

The LINFlexD Error Combined Interrupt can still be triggered by the buffer overrun. This interrupt is enabled by setting the Buffer Overrun Error Interrupt Enable (BOIE) bit in the LIN Interrupt enable register (LINIER). But the BOF bit will be cleared when the interrupt routine is entered, preventing the user to identify the source of error.

**Workaround:** Buffer overrun errors in UART FIFO mode can be detected by enabling only this source in the LIN Error Combined interrupt.

### **e3466: LINFlexD: Register bus aborts are not generated on illegal accesses to reserved addresses within the register address space of LINFlexD**

**Description:** Register bus aborts are not generated on illegal accesses to reserved addresses within the register address space of LINFlexD. This is applicable to LINFlex modules supporting master-only mode.

**Workaround:** None

### **e3219: MC\_CGM: System clock may stop for case when target clock source stops during clock switching transition**

**Description:** The clock switching is a two step process. The availability of the target clock is first verified. Then the system clock is switched to the new target clock source within two target clock cycles.

For the case when the FXOSC stops during the required two cycles, the switching process may not complete, causing the system clock to stop and prevent further clock switching. This may happen if one of the following cases occurs while the system clock source is switching to FXOSC:

- FXOSC oscillator failure
- SAFE mode request occurs, as this mode will immediately switch OFF the FXOSC (refer to ME\_SAFE\_MC register configuration)

**Workaround:** The device is able to recover through any reset event ('functional', 'destructive', internal or external), so typically either the SWT (internal watchdog) will generate a reset or, in case it is used in the application, the external watchdog will generate an external reset. In all cases the devices will restart properly after reset.

To reduce the probability that this issue occurs in the application, disable SAFE mode transitions when the device is executing a mode transition with the FXOSC as the system clock source in the target mode.

### **e3202: MC\_ME: Invalid Configuration not flagged if PLL is on while OSC is off.**

**Description:** PLL clock generation requires oscillator to be on. Mode configuration in which PLLON bit is "1" and OSCON bit is "0" is an invalid mode configuration. When ME\_XXX\_MC registers are attempted with such an invalid configuration, ME\_IS.I\_CONF is not getting set which is wrong. Eventually the mode transition did not complete and system hangs.

**Workaround:** Always program Oscillator to be on when PLL is required.

### **e3570: MC\_ME: Possibility of Machine Check on Low-Power Mode Exit**

**Description:** When executing from the flash and entering a Low-Power Mode (LPM) where the flash is in low-power or power-down mode, 2-4 clock cycles exist at the beginning of the RUNx to LPM transition during which a wakeup or interrupt will generate a checkstop due to the flash not being available on RUNx mode re-entry. This will cause either a checkstop reset or machine check interrupt.

**Workaround:** If the application must avoid the reset, two workarounds are suggested:

- 1) Configure the application to handle the machine check interrupt in RAM dealing with the problem only if it occurs
- 2) Configure the MCU to avoid the machine check interrupt, executing the transition into low power modes in RAM

There is no absolute requirement to work around the possibility of a checkstop reset if the application can accept the reset, and associated delays, and continue. In this event, the WKPU.WISR will not indicate the channel that triggered the wakeup though the F\_CHKSTOP flag will indicate that the reset has occurred. The F\_CHKSTOP flag could still be caused by other error conditions so the startup strategy from this condition should be considered alongside any pre-existing strategy for recovering from an F\_CHKSTOP condition.

### **e3247: MC\_ME: STANDBY0/HALT0/STOP0 modes cannot be entered if the FlexCAN peripheral is active**

**Description:** If any FlexCAN module is enabled in current mode by the ME\_RUN\_PCx/ME\_PCTLx registers of the MC\_ME and also enabled at the FlexCAN module, (MCR.B.MDIS=0), STANDBY0/HALT0/STOP0 modes will not be entered if the target low power mode is disabling the module, the device mode transition hangs.

**Workaround:** The FlexCAN module must be frozen (FLEXCANx\_MCR[FRZ]=1) in DRUN or RUNx mode before entering STANDBY0/HALT0/STOP0 modes.

### **e3574: MC\_RGM: A non-monotonic ramp on the VDD\_HV/BV supply can cause the RGM module to clear all flags in the DES register**

**Description:** During power up, if there is non-monotonicity in power supply ramp with a voltage drop > 100mV due to external factors, such as battery cranking or weak board regulators, the SoC may show a no flag condition (F\_POR==LVD12==LVD27==0).

Under these situations, it is recommended that customers use a workaround to detect a POR.

In all cases, initialization of the device will complete normally.

**Workaround:** The software workaround need only be applied when neither the F\_POR, LVD27 nor LVD12 flag is set and involves checking SRAM contents and monitoring for ECC errors during this process. In all cases, an ECC error is assumed to signify a power-on reset (POR).

Three suggestions are made for software workarounds. In each case, if POR is detected all RAM should be initialized otherwise no power-on condition is detected and it is possible to initialize only needed parts of RAM while preserving required information.

Software workaround #1 :

An area of RAM can be reserved by the compiler into which a KEY, such as 0x3EC1\_9678, is written. This area can be checked at boot and if the KEY is incorrect or an ECC error occurs, POR can be assumed and the KEY should be set. Use of a KEY increases detection rate to 31 bits(=<10e-9) or 23bits (= <5.10e-6) instead of 7-bit linked to ECC (=<10e-2)

Software workaround #2 :

When runtime data should be retained and RAM only fully re-initialized in the case of POR, a checksum should be calculated on the runtime data area after each data write. In the event of a reset where no flags are set, the checksum should be read and compared with one calculated across the data area. If reading the checksum and the runtime data area succeeds without an ECC error, and the checksums match, it is assumed that no POR occurred. The checksum could be a CRC, a CMAC or any other suitable hash.

Software workaround #3 :

Perform a read of memory space that is expected to be retained across an LVD reset. If there are no ECC errors, it can be assumed that an LVD reset occurred rather than a POR.

**e2958: MC\_RGM: Clearing a flag at RGM\_DES or RGM\_FES register may be prevented by a reset**

**Description:** Clearing a flag at RGM\_DES and RGM\_FES registers requires two clock cycles because of a synchronization mechanism. As a consequence if a reset occurs while clearing is on-going the reset may interrupt the clearing mechanism leaving the flag set.

Note that this failed clearing has no impact on further flag clearing requests.

**Workaround:** No workaround for all reset sources except SW reset.

Note that in case the application requests a SW reset immediately after clearing a flag in RGM\_xES the same issue may occur. To avoid this effect the application must ensure that flag clearing has completed by reading the RGM\_xES register before the SW reset is requested.

**e3049: MC\_RGM: External Reset not asserted if Short Reset enabled**

**Description:** For the case when the External Reset is enabled for a specific reset source at RGM\_FBRE and a short reset is requested for the same reset source at RGM\_FESS the External Reset is not asserted.

**Workaround:** None

**e2977: MC\_RGM: Long Reset Sequence Occurs on 'Short Functional' Reset Event**

**Description:** If a 'functional' reset source is configured to initiate a short reset sequence via setting of the appropriate RGM\_FESS bit and also configured to assert the external reset pad via setting of the appropriate RGM\_FBRE bit, its assertion will not initiate a short reset starting with PHASE3 but rather a long reset sequence starting with PHASE1.

**Workaround:** Do not configure 'functional' resets that are configured to initiate a short reset sequence to also assert the external reset pad. In other words, if RGM\_FESS[i] is '1', RGM\_FBRE[i] should be '0'.

**e3060: MC\_RGM: SAFE mode exit may be possible even though condition causing the SAFE mode request has not been cleared**

**Description:** A SAFE mode exit should not be possible as long as any condition that caused a SAFE mode entry is still active. However, if the corresponding status flag in the RGM\_FES register has been cleared, the SAFE mode exit may incorrectly occur even though the actual condition is still active.

**Workaround:** Software must clear the SAFE mode request condition at the source before clearing the corresponding RGM\_FES flag. This will ensure that the condition is no longer active when the RGM\_FES flag is cleared and thus the SAFE mode exit can occur under the correct conditions.

### e3209: NMI pin configuration limitation in standby mode

**Description:** NMI pin cannot be configured to generate Non Maskable Interrupt event to the core (WKPU\_NCR[NDSS] = "00") if the following standby mode is to be used:

- NMI pin enabled for wake-up event,
- standby exit sequence boot from RAM,
- code flash module power-down on standby exit sequence.

With following configuration following scenario may happen:

1. System is in standby
2. NMI event is triggered on PA[1]
3. System wakeup z0 core power domain.
4. z0 core reset is released and NMI event is sampled by core on first clock-edge.
5. z0 core attempt to fetch code at 0x10 address (IVPR is not yet initialized by application) and receive an exception since flash is not available
6. z0 core enter machine check and execution is stalled.

**Workaround:** If NMI is configured as wake-up source, WKPU\_NCR[NDSS] must be configured as "11". This will ensure no NMI event is triggered on the core but ensure system wakeup is triggered.

After standby exit, core will boot and configure its IVOR/IVPR, it may then re-configure WKPU\_NCR:DSS to the appropriate configuration for enabling NMI/CI/MCP.

### e3210: PA[1] pull-up enabled when NMI activated

**Description:** When NMI is enabled (either WKPU\_NCR[NREE] or WKPU\_NCR[NFEE] set to '1'), PA[1] pull-up is automatically activated independently from SIUL\_PCR1[WPS] and SIUL\_PCR1[WPE].

This has no effect during STANDBY mode. PA[1] pull-up is then correctly configured through WKPU\_WIPUER[IPUE[2]].

**Workaround:** None

### e3242: PB[10],PD[0:1] pins configuration during standby

**Description:** PB[10], PD[0:1] are the pins having both wake-up functionality and analog functionality.

As for all wake-up pins, it must be driven either high level or low level (possibly using the internal pull-up) during standby.

In case the pin is connected to external component providing analog signal, it is important to check that this external analog signal is either lower than  $0.2 \cdot VDD_{HV}$  or higher than  $0.8 \cdot VDD_{HV}$  not to incur extra consumption.

**Workaround:** None

**e3200: PIT events cannot be used to trigger ADC conversion incase BCTU runs on divided system clock**

**Description:** If BCTU operates on divided system clock (i.e MC\_CGM.CGM\_SC\_DC2.DIV0 NOT EQUAL 0x0), events from PIT timer cannot be used to trigger ADC conversion. In this case BCTU fails to latch the channel number to be converted. So BCTU will send the conversion request to ADC but the channel number will be corresponding to previous non-PIT conversion request or 0th channel in case no previous non-PIT event has occurred

**Workaround:** Always write MC\_CGM.CGM\_SC\_DC2.DIV0 to 0x0 to run BCTU at system frequency.

**e3270: Risk of increased Analog to Digital converter pad leakage under extreme current injection conditions**

**Description:** Post AEC latch-up stressing (100mA, 125C), there is a risk of leakage drift on the following pads:

176LQFP:

PA(3)/Physical pin 114

PA(7)/Physical pin 128

PA(10)/Physical pin 131

PA(11)/Physical pin 132

PE(12)/Physical pin 133

144LQFP:

PA(3)/Physical pin 90

PA(7)/Physical pin 104

PA(10)/Physical pin 107

PA(11)/Physical pin 108

PE(12)/Physical pin 109

100LQFP:

PA(3)/Physical pin 68

PA(7)/Physical pin 71

PA(10)/Physical pin 74

PA(11)/Physical pin 75

PE(12)/Physical pin 76

Increased leakage on these pads has been observed under AEC latch-up conditions, which are significantly above the +/- 5mA current injection spec. Leakage drift observed ranges from low nA to <10uA, depending on latch-up pulse width and wafer characteristics.

This leakage results from Current Injection stress, rather than a latch-up event. No increased leakage has been observed under spec current injection conditions.

**Workaround:** Adhere to current injection spec of +/- 5mA per pin. If performing AEC latch-up trials, be aware of risk of increased leakage on these pins.

### **e4405: SR bit of LINFLEXD GCR register is not cleared automatically by hardware**

**Description:** After setting the SR bit of GCR (Global Control Register) to reset the LinFlexD controller, this bit is not cleared automatically by the hardware, keeping the peripheral in reset state

**Workaround:** This bit should be cleared by software to perform further operations

### **e3119: SWT: SWT interrupt does not cause STOP0 mode exit**

**Description:** While in STOP0 mode, if the SWT is configured to generate an interrupt and the system clock is disabled (ME\_STOP0\_MC[SYSCLK] = 0xF), a SWT interrupt event will not trigger an exit from STOP0 mode.

Other internal or external wakeup events (RTC, API, WKUP pins) are not affected and will trigger a STOP0 exit independent of the ME\_STOP0\_MC[SYSCLK] configuration.

**Workaround:** If a SWT interrupt is to be used to wake the device during STOP0 mode, software may not disable the system clock (ME\_STOP0\_MC[SYSCLK] != 0xF).

### **e3236: Wakeup line functionality on PD[0], PD[1] not available in STANDBY**

**Description:** Wakeup line functionality is not available on ports PD[0], PD[1] during STANDBY mode. These pads are not supplied with ultra low power regulator, but are driven from main regulator which is switched off in STANDBY mode.

**Workaround:** None

### **e4146: When an ADC conversion is injected, the aborted channel is not restored under certain conditions**

**Description:** When triggered conversions interrupt the ADC, it is possible that the aborted conversion does not get restored to the ADC and is not converted during the chain. Vulnerable configurations are:

- Injected chain over a normal chain
- CTU trigger over a normal chain
- CTU trigger over an injected chain

When any of these triggers arrive whilst the ADC is in the conversion stage of the sample and conversion, the sample is discarded and is not restored. This means that the channel data register will not show the channel as being valid and the CEOCFRx field will not indicate a pending conversion. The sample that was aborted is lost.

When the trigger arrives during the final channel in a normal or injected chain, the same failure mode can cause two ECH/JECH interrupts to be raised.

If the trigger arrives during the sampling phase of the last channel in the chain, an ECH is triggered immediately, the trigger is processed and the channel is restored and after sampling/conversion, a second ECH interrupt occurs.

In scan mode, the second ECH does not occur if the trigger arrives during the conversion phase. In one-shot mode, the trigger arriving during the conversion phase of the last channel restarts the whole conversion chain and the next ECH occurs at completion of that chain.

**Workaround:** It is suggested that the application check for valid data using the CDR status bits or the CEOCFRx registers to ensure all expected channels have converted. This can be tested by running a bitwise AND and an XOR with either the JCMRx or NCMRx registers and the CEOCFRx registers during the ECH of JECH handler. Any non-zero value for  $(xCMRx \& (xCMRx \oplus CEOCFRx))$  indicates that a channel has been missed and conversion should be requested again.

Spurious ECH/JECH interrupts can be detected by checking the NSTART/JSTART flags in the ADC Module Status Registers – if the flag remains set during an ECH/JECH interrupt then another interrupt will follow after the restored channel or chain has been sampled and converted.



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